Effective July 2017 Supersedes June 2012

HCM1103 High current power inductors



Product features

- 11.5 x 10.3 x 3.0 mm maximum surface mount package
- Iron powder core material
- Magnetically shielded, low EMI
- High current carrying capacity, low core losses
- Inductance range from 0.12 μH to 22.0 μH
- Current range from 3.0 A to 75 A
- Halogen free, lead free, RoHS compliant

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- Point-of-load modules
- Desktop and server VRMs and EVRDs
- Base station equipment
- Notebook and laptop regulators
- Battery power systems
- Graphics cards
- Data networking and storage systems

Environmental Data

- Storage temperature range (Component): -55 °C to +125 °C
- Operating temperature range: -55 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant





Product Specifications

Part	OCL1	FLL min. ²	I _{rms³}	I _{sat} 4 @ +25 °C	DCR (m Ω) @	DCR (mΩ) @	
Number ⁶	±20% (µH)	(µH)	(A)	(A)	+20 °C Typical	+20 °C Maximum	K-Factor ⁵
HCM1103-R12-R	0.12	0.07	30	75	0.55	0.61	1200
HCM1103-R36-R	0.36	0.26	23	28	1.10	1.30	711
HCM1103-R47-R	0.47	0.33	20	26	1.50	2.00	515
HCM1103-R68-R	0.68	0.38	21	23	2.90	3.40	510
HCM1103-1R0-R	1.0	0.56	15	21	5.50	6.00	377
HCM1103-2R2-R	2.2	1.2	13	16	8.40	9.00	264
HCM1103-3R3-R	3.3	1.9	9.0	14	14.5	16.0	230
HCM1103-4R7-R	4.7	2.6	7.0	13	20.5	22.5	205
HCM1103-8R2-R	8.2	4.6	5.0	8.5	35.0	38.5	153
HCM1103-100-R	10.0	5.6	5.0	7.5	40.0	44.0	141
HCM1103-150-R	15.0	8.4	4.0	6.0	59.0	65.0	114
HCM1103-220-R	22.0	12.3	3.0	5.0	90.0	99.0	91

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{rms}, 0.0 Adc @ +25 $^\circ\text{C}$

2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 $V_{rms},\,I_{sat}$ @ +25 °C.

3. Imms: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application. 5. K-factor: Used to determine $B_{p\text{-}p}$ for core loss (see graph). $B_{p\text{-}p}$ = K * L * $\Delta I.$ $B_{p\text{-}p}$:(Gauss), K: (K-factor from table),

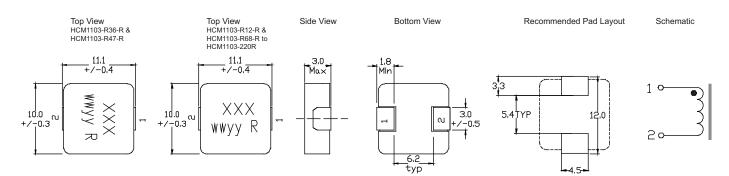
L: (Inductance in μ H), Δ I (peak-to-peak ripple current in Amps). 6. Part Number Definition: HCM1103-xxx-R

HCM1103 = Product code and size xxx= Inductance value in µH, R = decimal point,

if no R is present then third character = number of zeros.

-R suffix = RoHS compliant

Dimensions (mm)



Part Marking: xxx = Inductance value in uH, R = decimal point, if no R is present then third character = # of zeros. wwyy = (Date code), R = Revision Level

All soldering surfaces to be coplanar within 0.10 millimeters.

Tolerances are ±0.3 millimeters unless stated otherwise.

HCM1103-R36-R and HCM1103-R47-R Color: Black

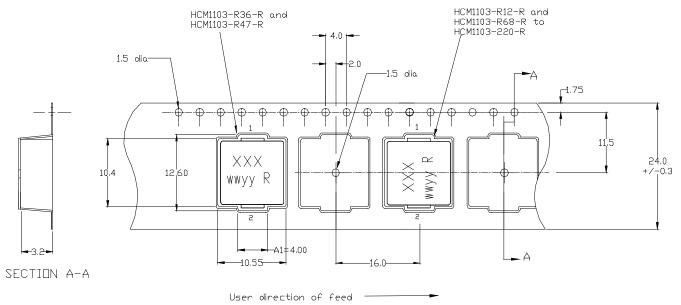
HCM1103-R12-R and HCM1103-R68-R to HCM1103-220-R Color : Top Grey

^{4.} Isat: Peak current for approximately 30% rolloff at +25 °C

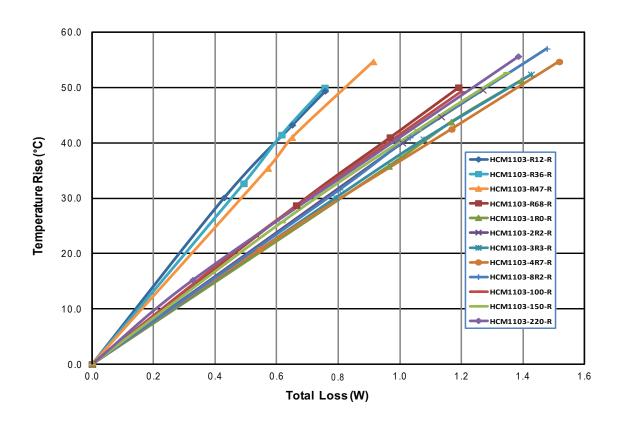
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Packaging information (mm)

Supplied in tape and reel packaging, 1000 parts per 13" diameter reel.

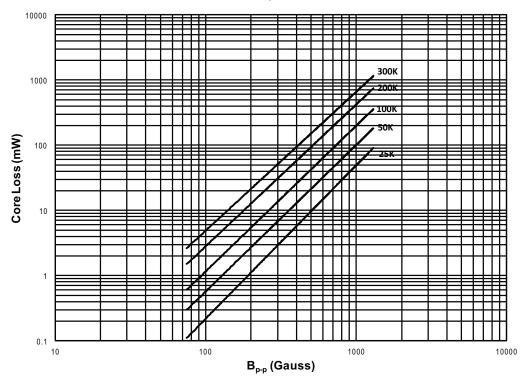


Temperature rise vs. total loss

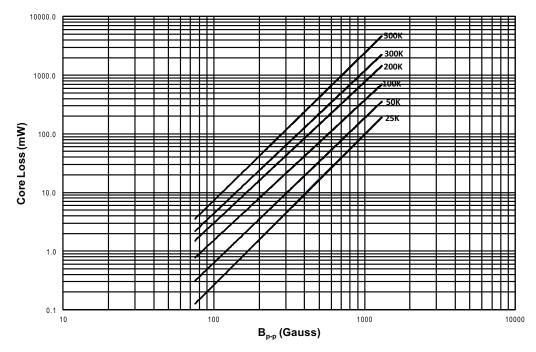


Core loss vs. Bp-p

HCM1103-; R36-R and R47-R

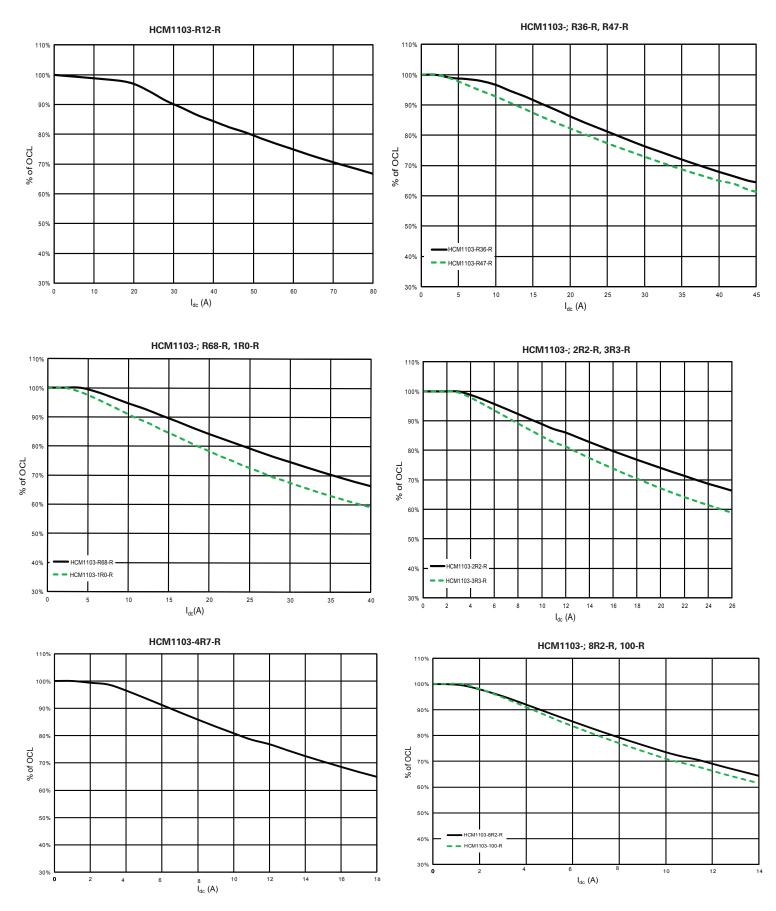






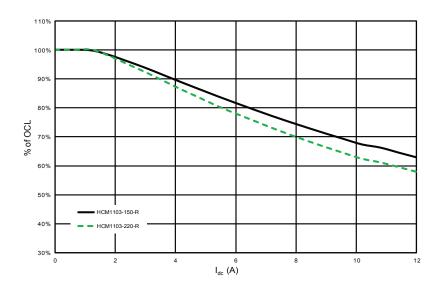
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Inductance characteristics



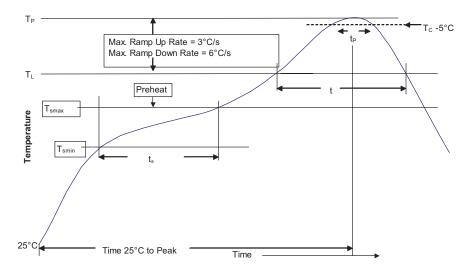
Technical Data **4449** Effective July 2017

Inductance characteristics



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Solder reflow profile



$-_{T_c - 5^{\circ}C}$ Table 1 - Standard SnPb Solder (T_c)

Package Thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak • Temperature min. (T _{smin})	100°C		
• Temperature max. (T _{smax})	150°C	200°C	
• Time (T _{smin} to T _{smax}) (t _s)	60-120 Seconds	60-120 Seconds	
Average ramp up rate T _{smax} to T _p	3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL) Time at liquidous (tL)	183°C 60-150 Seconds	217°C 60-150 Seconds	
Peak package body temperature (Tp)*	Table 1	Table 2	
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c)	20 Seconds**	30 Seconds**	
Average ramp-down rate (T _p to T _{smax})	6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.	

* Tolerance for peak profile temperature (T_n) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.

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